#12 Declaration JMcCuille 10/29/02

PATENT APPLICATION
Serial No. 09/744,424
Attorney Docket No. 1217-010064

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Group Art Unit 2827 :

In re Application of :

Toshiyuki NAKAMURA et al. : **SHEET FOR FORMING A PRINTED WIRING BOARD**

Serial No. 09/744,424 :

Filed January 24, 2001 :

Examiner Kamand Cuneo :

Pittsburgh, Pennsylvania

DECLARATION UNDER 37 CFR § 1.131

Commissioner for Patents
Washington, D.C. 20231

We, Toshiyuki Nakamura, Hideto Tanaka, Akira Ichiryu, Motonobu Takahashi, Masahito Ishii, and Daisuke Arai, hereby declare as follows:

1. We are the named inventors of the invention described and claimed in the above-captioned application.

2. Japanese Patent Application No. 144275/1999, filed May 25, 1999, a copy of which is attached hereto, from which the present U.S. application ultimately claims priority, discloses a printed wiring board-forming sheet that includes an insulating resin sheet, which may be a polyimide, polyester, polypropylene, polyphenylene sulfide, polyvinylidene chloride, Eval, glass epoxy, or a BT resin, having a through hole inserted and filled with a conductive metal chip of substantially the same shape as the hole, where, optionally, a

conductive layer is formed on at least one surface of the insulating resin sheet having a hole inserted and filled with a conductive metal chip, the conductive metal layer, which may be formed by a foil of a metal or a metal-alloy or a wiring pattern, and the conductive metal chip, which may be formed by punching at least one conductive metal sheet selected from a solder sheet, a solder plated metal sheet, a copper sheet, or a copper alloy sheet, being connected electrically with each other.

The invention disclosed by Japanese Patent Application No. 144275/1999 is the invention as claimed in the present United States application.

3. The filing of the Japanese Patent Application No. 144275/1999 on May 25, 1999 and subsequently filing an international application on January 5, 2000 and United States national phase application on January 24, 2001, all within the timeframe required by the Patent Cooperation Treaty, demonstrates the required evidence of conception, diligence, and constructive reduction of the claimed invention.

4. We declare further that all statements made herein of our own knowledge are true and that all statements made on information and belief are believed to be true, and further that these statements are made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment or both, under Section 1001 of Title 18 of the United States Code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Toshiyuki Nakamura
Toshiyuki Nakamura

Sep. 28, 2002
Date

Hideto Tanaka
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Sep. 24. 2002
Date

Akira Ichiryu
Akira Ichiryu

Sep. 18, 2002
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